Features

• The board integrates:
  – iNEMO inertial module LSM6DSO
  – Magnetometer LIS2MDL
  – Pressure sensor LPS22HH
  – Humidity sensor HTS221
• RoHS compliant

Applications

• Personal computing
• Tablets and mobile phones with OIS/EIS and AR/VR systems
• Gaming and virtual reality input devices
• Wellness and wearable devices
• Drones and robotics
• IoT devices including industrial and factory automation systems

Description

The enhanced embedded sensor topology of the STDESMKI128V7 MEMS sensor module helps you save development time and effort when developing smart, creative prototypes for a wide range of applications.

This compact board integrates the iNEMO inertial module (LSM6DSO) with 3D accelerometer and 3D gyroscope that is particularly suitable for smartphones with OIS/ EIS and AR/VR systems, a magnetometer (LISMDL), a dust-resistant full-mold absolute pressure sensor (LPS22HH), and a relative humidity and temperature sensor (HTS221).
1 PCB overview

Figure 1. PCB overview
Figure 2. STDES-MKI128V7 circuit schematic
## Revision history

**Table 1. Document revision history**

<table>
<thead>
<tr>
<th>Date</th>
<th>Version</th>
<th>Changes</th>
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<tbody>
<tr>
<td>20-Jul-2020</td>
<td>1</td>
<td>Initial release.</td>
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